

EAST Search History**EAST Search History (Prior Art)**

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|-------|---|---|------------------|---------|---------------------|
| L1 | 1 | "10585729" | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2011/01/26 19:02 |
| S1 | 1 | ("20080048009").PN. | US-PGPUB; USPAT; USOCR | OR | OFF | 2009/08/17 09:59 |
| S2 | 4 | ("6189771") or ("6680128") or ("6951666") or ("5837119").PN. | US-PGPUB; USPAT; USOCR | OR | OFF | 2009/08/17 10:05 |
| S3 | 99 | (particle or particulate or powder) with (flake) with solder | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2009/08/17 10:09 |
| S4 | 17 | (resin or epoxy) with (coat \$3 or layer or film) same (particle or particulate or powder) with (flake) same solder | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2009/08/17 10:21 |
| S5 | 67 | (resin or epoxy or polymer \$3) with (flake) with (metal\$4) same solder | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2009/08/17 10:28 |
| S6 | 13513 | (resin or epoxy or polymer \$3) with (coat\$3 or layer or film) with (solder) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2009/08/17 10:45 |
| S7 | 75 | S6 same (flake or flat) with (metal\$4) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2009/08/17 10:46 |

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| S8 | 2641 | bent with circuit board same (solder\$3) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2011/01/25 20:09 |
| S9 | 82 | bent with circuit board same (solder\$3) ball | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2011/01/25 20:09 |
| S10 | 21 | bent with component same (solder\$3) ball | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2011/01/25 20:11 |
| S11 | 528 | (various or different) with (siz\$3 or diameter) with (solder\$3 near (ball or bump)) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2011/01/25 20:12 |
| S12 | 200 | (various or different) with (siz\$3 or diameter) with (solder\$3 near (ball or bump)) same substrate | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2011/01/25 20:12 |
| S13 | 3 | ("2004/0227236").URPN. | USPAT | ADJ | ON | 2011/01/25 20:15 |
| S14 | 36 | (bent or curv\$3) with component same (solder \$3) ball | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2011/01/25 20:19 |
| S15 | 50 | (warp\$3) with component same (solder\$3) ball | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2011/01/25 20:22 |
| S16 | 15 | "6189771" | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2011/01/25 20:35 |

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| S17 | 10 | ("20040177997" "5234149" "5672542" "6121062" "6189771" "6297560" "6495397" "6566234" "7244634"). PN. OR ("7632710"). URPN. | US-PGPUB; USPAT; USOCR | ADJ | ON | 2011/01/25 20:36 |
| S18 | 15 | "6189771" | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2011/01/25 20:40 |
| S19 | 591 | flux same (iminodiacetic acid or \$3hydroxybenzoic acid or \$3phenylalanine or mesaconic acid) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2011/01/25 20:46 |
| S20 | 59 | flux with (iminodiacetic acid or \$3hydroxybenzoic acid or \$3phenylalanine or mesaconic acid) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2011/01/25 20:47 |
| S21 | 1 | ("6,680,128").PN. | US-PGPUB; USPAT; USOCR | OR | OFF | 2011/01/26 16:14 |
| S22 | 63 | flux same (\$4hydroxy \$1benzoic near acid) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2011/01/26 16:22 |
| S23 | 2 | "20080048009" | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2011/01/26 16:53 |
| S24 | 13067 | solder (bump or ball) same (electrodes) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2011/01/26 17:02 |
| S25 | 1292 | solder (bump or ball) same (electrodes) same (bga) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2011/01/26 17:03 |

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| S26 | 1292 | solder (bump or ball) same (electrodes) same (bga) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2011/01/26 17:03 |
| S27 | 105 | (bga or semiconductor) same (solder near2 (ball or bump)) with (various or different) near2 (size or diameter) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2011/01/26 17:24 |

EAST Search History (Interference)

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1/ 26/ 2011 7:31:18 PM

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